

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	29550	silicon near4 ((aluminum adj oxide) (boron adj nitride))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:03
L2	75	1 with (encapsulant encapsulated encapsulating (sealing near resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:24



L14	0	2 and "w/m.k."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:20
L15	0	2 and "1.5w/m.k."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:05
L16	2	2 with (thermal adj conductivity)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:05
L17	5	2 same (thermal adj conductivity)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:14
L18	12	2 and (thermal near1 conductivity)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:15
L19	1	"w/m.k."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:20
L20	0	"1.5w/m.k."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:20
L21	0	"1.5 w/m.k."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:21
L22	0	"1.5W/m.K."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:21
L23	1	"W/m.K."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:22
L24	831	"W/m.K"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:22
L25	3	24 with (thermal near1 conductivity) with (encapsulant encapsulated encapsulating (sealing near resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:24
L26	603	24 with (thermal near1 conductivity)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:24
L27	3	26 same (encapsulant encapsulated encapsulating (sealing near resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:24
L28	26	26 and (encapsulant encapsulated encapsulating (sealing near resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:24